## **CLEAN VERSION OF PENDING CLAIMS**

## METHOD AND APPARATUS FOR DISSIPATING HEAT FROM AN ELECTRONIC DEVICE

Applicant: George K. Korinsky et al. Serial No.: 09/615,922

1. An apparatus for dissipating heat from an electronic device, the apparatus comprising: a housing adapted to be closely fitted to a heat sink; the housing having a first end and a second end; and

an air moving device adapted to be coupled to a first end of the housing, the air moving device to move air through the housing.

- 2. (Amended) The apparatus of claim 1 further comprising an air duct coupled to the second end of the housing, the air duct to direct the flow of air from an exterior of a chassis to the housing.
- 3. The apparatus of claim 2 wherein the air duct is a flexible hose.
- 4. The apparatus of claim 3 wherein the air duct is an extendable hose.
- 5. The apparatus of claim 2 wherein the air duct is rigid.
- 6. The apparatus of claim 1 wherein the air moving device is a fan.
- 7. The apparatus of claim 6 wherein the fan has a diameter of between about 20 millimeters and about 120 millimeters.
- 8. The apparatus of claim 6 wherein the fan has a diameter of about 60 millimeters.



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9. The apparatus of claim 6 wherein the fan is coupled to the housing at a distance from the heat sink that is about equal to a diameter of the fan.

- 10. The apparatus of claim 6 wherein the fan is coupled to the housing at a distance from the heat sink that is less than a diameter of the fan.
- 11. An integrated circuit cooling system comprising:

  means to generate a flow of air through a plurality of fins of a heat sink; and

  means to contain and guide air movement through the plurality of fins of the heat sink

  wherein the means to contain and guide air movement substantially eliminates blowby.
- 12. The integrated circuit cooling system of claim 11 further comprising means to direct air external to a chassis to the means to contain and guide air movement.
- 13. The integrated circuit cooling system of claim 11 wherein the means to generate a flow of air exhausts the means to contain and guide air movement.
- 14. The integrated circuit cooling system of claim 10 wherein the means to generate a flow of air pressurizes the means to contain and guide air movement.
- 15. A computerized system comprising:
  - a chassis;
  - an integrated circuit board mounted in the chassis;
  - a processor coupled to the integrated circuit board; and
- a processor cooling system coupled to the processor, the processor cooling system comprising:
  - a heat sink coupled to the processor;
  - a housing coupled to the heat sink, the housing positioned in close proximity to



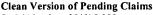
the heat sink; and

a fan coupled to the housing, the fan to create a flow of air through the housing.

- 16. The computerized system of claim 15 further comprising a first air duct coupled to the housing and to the chassis, the air duct to channel external ambient air to the heat sink.
- 17. The computerized system of claim of claim 16 further comprising a second air duct coupled to the housing and to the chassis, the second air duct to channel heated air away from the heat sink and out of the chassis.
- 18. The computerized system of claim 15 further comprising: a second fan coupled to the housing; and an air duct coupled to the housing.
- 19. The computerized system of claim 15 further comprising:
  - a second processor coupled to the integrated circuit board;
  - a second heat sink coupled to the second processor;
- a second housing coupled to the second heat sink, the second housing positioned in close proximity to the second heat sink;
  - a second fan coupled to the second housing; and
  - a housing connector coupled to the first housing and the second housing.
- 20. (Amended) A method of assembling a cooling system for an integrated circuit, the method comprising:

closely coupling a housing to a heat sink for an integrated circuit; and coupling a fan to the housing.





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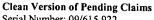
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- 21. The method of claim 20 further comprising coupling one or more cooling attachments to the housing.
- 22. The method of claim 21 wherein coupling one or more cooling attachments to the housing comprises coupling an air duct to the housing and to a chassis.
- 23. (Amended) The method of claim 22 further comprising coupling a cooling attachment to the fan.
- The method of claim 23 wherein coupling a cooling attachment to the fan further 24. comprises coupling an extendable, flexible hose to the fan and to the chassis.
- 25. (Amended) A method of cooling an integrated circuit, the method comprising: generating a flow of external ambient air through an air duct to a housing fitted closely over a first heat sink; and drawing the flow of external ambient air over the first heat sink.
- 26. (Amended) The method of claim 25 further comprising drawing the flow of external ambient air over a second heat sink positioned in-line with the first heat sink.
- 27. The method of claim 25 further comprising exhausting heated air drawn over the first heat sink and the second heat sink into a chassis.
- 28. A kit of parts for an electronic component cooling system, the kit comprising: one or more heat sink housings adapted to fit over a heat sink for an electronic component; and

a plurality of interchangeable cooling attachments adapted to be combined with the one or more heat sink housings to form an electronic component cooling system.

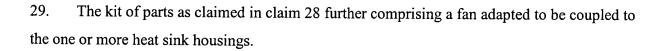




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30. The kit of parts as claimed in claim 28 wherein the plurality of cooling attachments are selected from the group consisting of: a housing air duct adapter, an air inlet chassis adapter, a housing fan adapter, a housing connector, a chassis fan adapter, and a splitter.